



Efficient deposition with patented flood system

The Plate Through Hole metallization quality and uniformity determines the quality of the subsequent electrodeposited copper and thus the long-term reliability of the board.

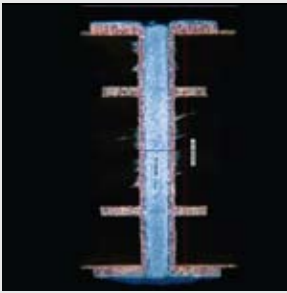
Areas of application

- Conventional PCB and HDI applications
- Electroless copper (compatible with all chemistries)
- Palladium-based direct metallization
- Graphite
- Carbon Black
- Conductive polymer • For flexible material or reel to reel

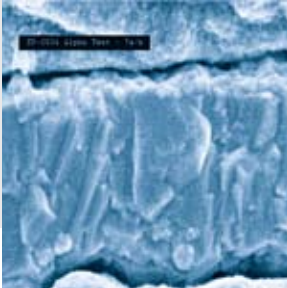
Features and benefits

- Operating elements clearly placed and easily accessible
- Specific designed fluid dynamics for uniform results
- "Tsunami" forced flood system with HDF technology
- Long term cooperation with all major suppliers of Chemistry
- Inline cartridge filtration
- Same process condition each panel
- Small sumps with sloped bottoms to drain





Through hole cross section



Grain structure



Standard configuration of 1 m/min EVOLUTION Electroless Copper System

